



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/388,826  
Filing Date ..... September 1, 1999  
Inventor ..... Weimin Li et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2813  
Examiner ..... E. Kielin  
Attorney's Docket No. .... MI22-1208  
Title: Low k Interlevel Dielectric Layer Fabrication Methods

**RESPONSE TO September 25, 2001 INTERVIEW SUMMARY**

To: Box Non-Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Bernard Berman (Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
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Sir:

Responsive to the Interview Summary dated September 25, 2001,  
Applicant respectfully requests reconsideration of the above-referenced  
application in view of the remarks that follow.

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